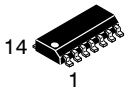
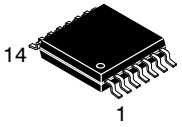
Quad 2-Input Exclusive-OR Gate

74AC86



SOIC14
CASE 751EF



TSSOP−14 WB
CASE 948G

General Description

The 74AC86 contains four, 2−input exclusive−OR gates.

Features

- I_{CC} Reduced by 50%
- Outputs Source/Sink 24 mA
- These Devices are Pb−Free, Halide Free and are RoHS Compliant

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Supply Voltage	V_{CC}	−0.5 to +6.5	V
DC Input Diode Current V_I = 0.5 V V_I = V_{CC} + 0.5 V	I_{IK}	 −20 +20	mA
DC Input Voltage	V_I	−0.5 to V_{CC} + 0.5	V
DC Output Diode Current V_O = −0.5 V V_O = V_{CC} + 0.5 V	I_{OK}	 −20 +20	mA
DC Output Voltage	V_O	−0.5 to V_{CC} + 0.5	V
DC Output Source or Sink Current	I_O	±50	mA
DC V_{CC} or Ground Current per Output Pin	I_{CC} or I_{GND}	±50	mA
Storage Temperature	T_{STG}	−65 to +150	°C
Junction Temperature (PDIP)	T_J	140	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

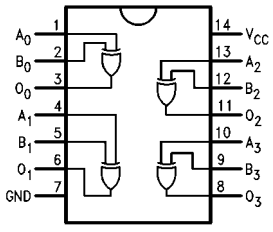


Figure 1. Connection Diagram

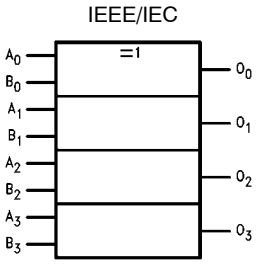
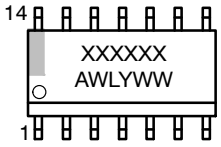
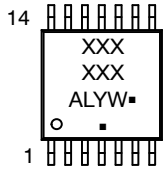


Figure 2. Logic Symbol

MARKING DIAGRAMS





AC86 = Specific Device Code
A = Assembly Location
L, WL = Wafer Lot
Y = Year
W, WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

PIN DESCRIPTION

Pin Names	Description
A_0−A_3	Inputs
B_0−B_3	Inputs
O_0−O_3	Outputs

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage	2.0	6.0	V
V_I	Input Voltage	0	V_{CC}	V
V_O	Output Voltage	0	V_{CC}	V
T_A	Operating Temperature	−40	85	°C
$\Delta V/\Delta t$	Minimum Input Edge Rate V_{IN} from 30% to 70% V_{CC} V_{CC} @ 3.3 V, 4.5 V, 5.5 V	125		mV/ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = −40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = −50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	V_{IN} = V_{IL} or V_{IH} I_{OH} = −12 mA I_{OH} = −24 mA I_{OH} = −24 mA (Note 1)
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	V_{IN} = V_{IL} or V_{IH} I_{OL} = 12 mA I_{OL} = 24 mA I_{OL} = 24 mA (Note 1)
I_{IN} (Note 3)	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	Minimum Dynamic Output Current (Note 2)	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	−75	mA	V_{OHD} = 3.85 V Min
I_{CC} (Note 3)	Maximum Quiescent Supply Current	5.5	–	2.0	20.0	μA	V_{IN} = V_{CC} or GND

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0 ms, one output loaded at a time.
3. I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	T_A = +25°C, C_L = 50 pF			T_A = −40°C to +85°C, C_L = 40 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PHL}	Propagation Delay Inputs to Outputs	3.3 5.0	2.0 1.5	6.0 4.5	11.5 8.5	1.5 1.0	12.5 9.5	ns
t_{PLH}	Propagation Delay Inputs to Outputs	3.3 5.0	2.0 1.5	6.5 4.5	11.5 8.5	1.5 1.0	12.5 9.0	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Typ	Unit	Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = OPEN
C_{PD}	Power Dissipation Capacitance	35	pF	V_{CC} = 5.0 V

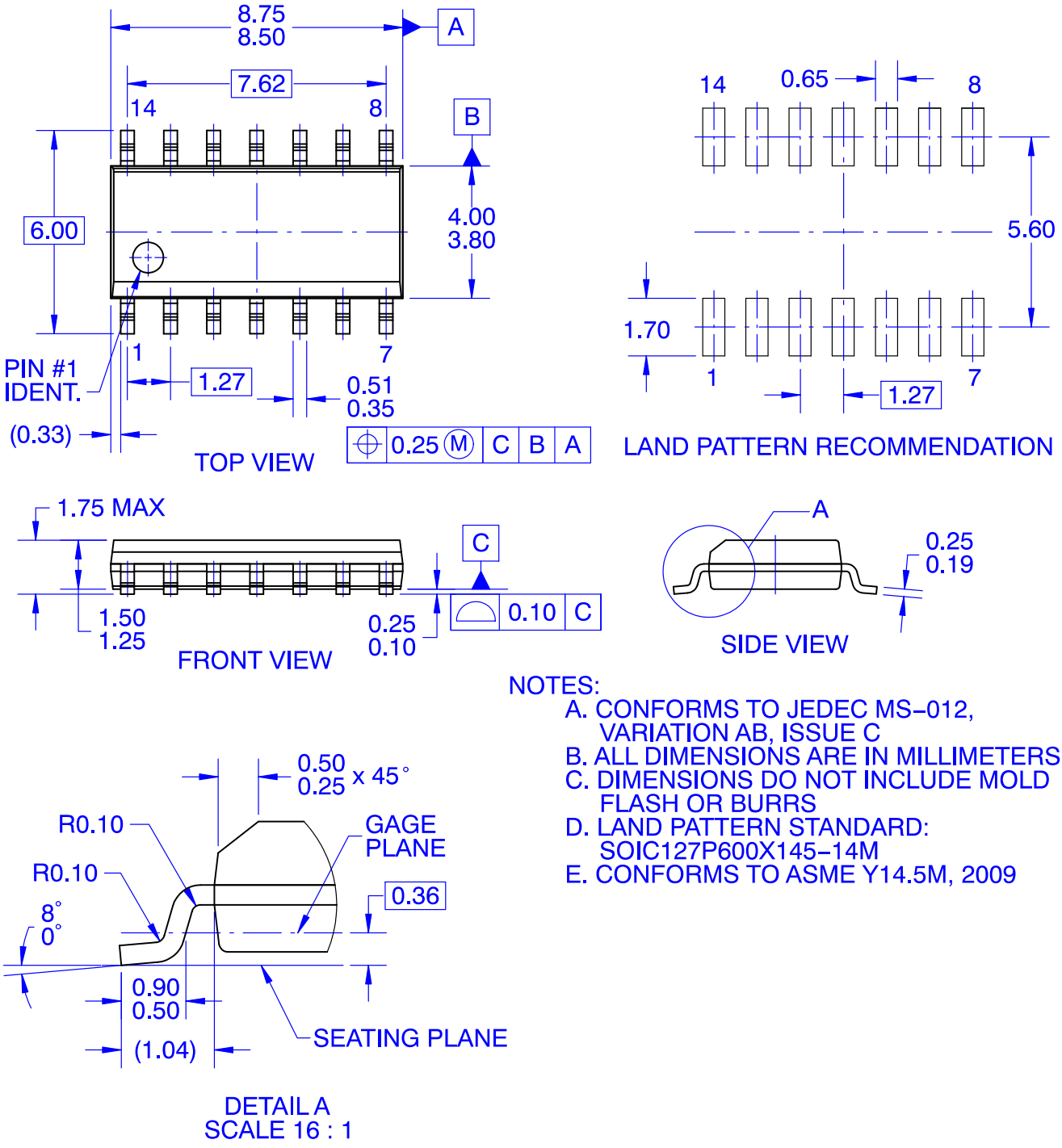
ORDERING INFORMATION

Device	Marking	Package	Shipping†
74AC86MTCX	AC 86	TSSOP−14	2500 Units / Tape & Reel
74AC86SCX	AC86	SOIC−14	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SOIC14
CASE 751EF
ISSUE O

DATE 30 SEP 2016



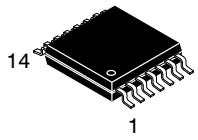
NOTES:
A. CONFORMS TO JEDEC MS–012, VARIATION AB, ISSUE C
B. ALL DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
D. LAND PATTERN STANDARD: SOIC127P600X145–14M
E. CONFORMS TO ASME Y14.5M, 2009

DOCUMENT NUMBER:	**98AON13739G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**SOIC14**	**PAGE 1 OF 1**

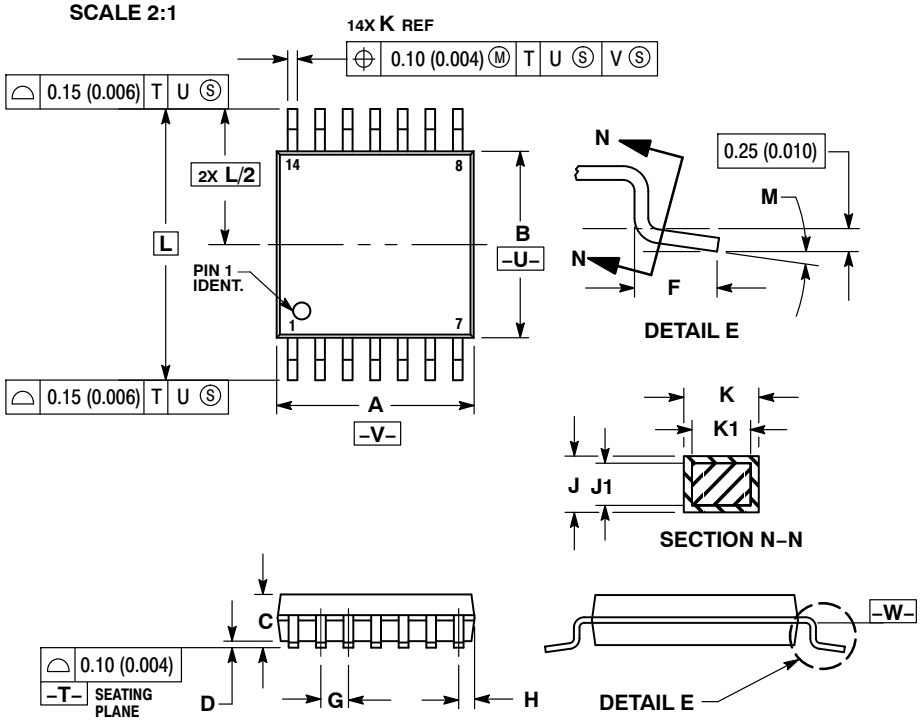
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TSSOP−14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016



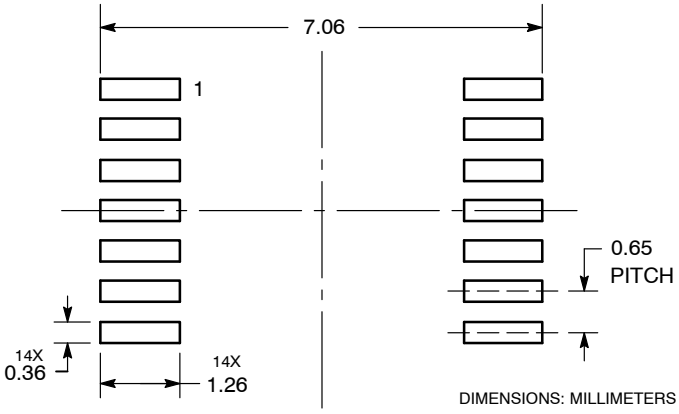
SCALE 2:1



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

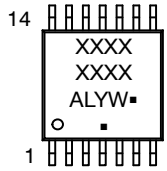
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	−−−	1.20	−−−	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98ASH70246A**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**TSSOP−14 WB**	**PAGE 1 OF 1**

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales